

Title (en)  
MODULAR FLOORING SYSTEMS AND METHODS

Title (de)  
MODULARE BODENSYSTEME UND VERFAHREN

Title (fr)  
SYSTEMES ET PROCEDES DE POSE DE REVETEMENTS DE SOL MODULAIRES

Publication  
**EP 1055273 A1 20001129 (EN)**

Application  
**EP 99906993 A 19990212**

Priority  
• US 9903122 W 19990212  
• US 7465498 P 19980213

Abstract (en)  
[origin: WO9941814A1] Modular flooring systems and methods using at least one free-lay support module. The free-lay support module includes a baseplate and a frame member having a first arm and a second arm that meet and form an angle. Replaceable wear surface modules with or without a backing structure fit within the baseplate. The top of frame partially overlays the replaceable wear surface modules that may be carpet, carpet tile, vinyl flooring, wood flooring, wood parquet flooring or a variety of other materials. In still another embodiment, this invention provides for a free-lay support module that is self-contouring or self-leveling. In yet another embodiment this invention provides a replaceable wear surface modular flooring structure utilizing floor grid members having a "horizontal arm" and a "vertical arm", each of which are in the form of an open U-shaped channel. A trim member has a decorative upper surface and any of a variety of cross-sectional shapes with downward facing members that engage the floor grid members providing a decorative and protective cap on the top of such grid members. In still another embodiment, power systems, communications systems, and/or cable systems reside within the channels.

IPC 1-7  
**H02G 3/28**; **E04F 15/024**

IPC 8 full level  
**E04F 15/02** (2006.01); **E04F 15/024** (2006.01); **H02G 3/00** (2006.01); **H02G 3/38** (2006.01)

CPC (source: EP)  
**E04F 15/02** (2013.01); **E04F 15/02405** (2013.01); **H02G 3/285** (2013.01)

Citation (search report)  
See references of WO 9941814A1

Designated contracting state (EPC)  
DE FR GB NL

DOCDB simple family (publication)  
**WO 9941814 A1 19990819**; AU 2677099 A 19990830; BR 9907890 A 20001031; CA 2320802 A1 19990819; CA 2320802 C 20060801; EP 1055273 A1 20001129; JP 2002503781 A 20020205

DOCDB simple family (application)  
**US 9903122 W 19990212**; AU 2677099 A 19990212; BR 9907890 A 19990212; CA 2320802 A 19990212; EP 99906993 A 19990212; JP 2000531892 A 19990212